

AMENDMENTS TO THE CLAIMS

Claim 1 (twice amended): A process for ~~pattern formation~~ patterning a substrate

comprising the steps of:

coating a carrier with a photosensitive material,

exposing the photosensitive material to a pattern of radiation, and

physically transferring the exposed material to a the substrate.

Claim 2 (twice amended): The process of claim 1, further comprising the step of

developing the exposed photosensitive material after the material ~~is~~ has been

transferred to the substrate.

Claim 3 (original): The process of claim 2, in which the substrate is a curved surface, and

the carrier is manufactured from a flexible material.

Claim 4 (original): The process of claim 1, in which

the carrier is fabricated from the group of materials consisting of quartz, glass,

silicon dioxide, silicon nitride, sodium chloride, silicon, and gallium arsenide.

Claim 5 (original): The process of claim 1, in which

the carrier is fabricated from a polymeric material.

Claim 6 (original): The process of claim 1, in which the

photosensitive material is a photoresist.

Claim 7 (original): The process of claim 1, in which
the exposure step comprises exposure to UV photons.

Claim 8 (original): The process of claim 1, in which the
photosensitive material is sensitive to electron beam exposure, and the
exposure step comprises exposure to electron beams.

Claim 9 (original): The process of claim 1, further comprising the step of
coating the photosensitive material on the carrier
with an adhesion layer.

Claim 10 (original): The process of claim 9, in which
a removal layer is formed between the carrier and the photosensitive material.

Claim 11 (original): The process of claim 10, in which
the adhesion layer comprises multiple layers.

Claim 12 (original): The process of claim 1, further comprising the step of
coating the substrate with an adhesion layer.

Claim 13 (original): The process of claim 12, in which
a removal layer is formed between the carrier and the photosensitive material.

Claim 14 (original): The process of claim 12, in which
the adhesion layer comprises multiple layers.

Claim 15 (original): The process of claim 14, further comprising the step of
coating the photosensitive material with an additional adhesion layer.

Claim 16 (original): The process of claim 15, in which
the additional adhesion layer comprises multiple layers.

Claim 17 (original): The process of claim 1 in which
the transfer of the photosensitive material to the substrate comprises
bringing the carrier with the material in close physical proximity to the
substrate and pressing the carrier, substrate, and intervening films together.

Claim 18 (original): The process of claim 17, in which
the carrier and the substrate are heated above room temperature while in close
physical proximity.

Claim 19 (original): The process of claim 17, in which
the carrier and substrate are exposed to radiation while in close physical
proximity.

Claim 20 (original): The process of claim 19, in which
the radiation comprises UV photons.

Claim 21 (original): The process of claim 17, in which
a solvent is introduced to dissolve a part of the intervening films.

Claim 22 (original): The process of claim 17, further comprising the step of
alignment between the carrier and the substrate.

Claim 23 (original): The process of claim 17,
further comprising the step of
alignment between the exposed material and the substrate.

Claim 24 (withdrawn).

Claim 25 (withdrawn).

Claim 26 (withdrawn).

Claim 27 (withdrawn).

Claim 28 (new): The process of claim 2, further comprising the step of
etching the substrate after the exposed photosensitive material has been
developed.